

General Description

The ultra-small MAX1682/MAX1683 monolithic, CMOS charge-pump voltage doublers accept input voltages ranging from +2.0V to +5.5V. Their high voltage-conversion efficiency (over 98%) and low operating current (110µA for MAX1682) make these devices ideal for both battery-powered and board-level voltage-doubler applications.

Oscillator control circuitry and four power MOSFET switches are included on-chip. The MAX1682 operates at 12kHz and the MAX1683 operates at 35kHz. A typical application includes generating a 6V supply to power an LCD display in a hand-held PDA. Both parts are available in a 5-pin SOT23 package and can deliver 30mA with a typical voltage drop of 600mV.

Features

- ♦ 5-Pin SOT23 Package
- → +2.0V to +5.5V Input Voltage Range
- ♦ 98% Voltage-Conversion Efficiency
- † 110µA Quiescent Current (MAX1682)
- **♦** Requires Only Two Capacitors
- ♦ Up to 45mA Output Current

Applications

Small LCD Panels

Cell Phones

Handy-Terminals

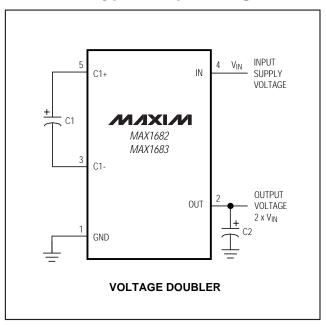
PDAs

Ordering Information

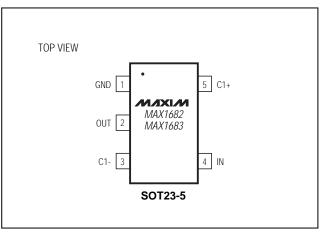
| PART | TEMP. RANGE | PIN- PACKAGE | SOT TOP MARK |
|--------------|----------------|-----------------|-----------------|
| MAX1682C/D | 0°C to +70°C | Dice* | _ |
| MAX1682EUK-T | -40°C to +85°C | 5 SOT23-5 | ACLL |
| MAX1683C/D | 0°C to +70°C | Dice* | _ |
| MAX1683EUK-T | -40°C to +85°C | 5 SOT23-5 | ACCM |

Note: These parts are available in tape-and-reel only. Minimum order quantity is 2500 pieces.

Typical Operating Circuit



Pin Configuration



NIXIN

Maxim Integrated Products 1

^{*}Dice are tested at $T_A = +25$ °C.

ABSOLUTE MAXIMUM RATINGS

| IN to GND+6V to -0.3V | Operating Temperature Range |
|-------------------------------------------------------|------------------------------------------|
| OUT to GND+12V, V _{IN} - 0.3V | MAX1682EUK/MAX1683EUK40°C to +85° |
| OUT Output Current50mA | Junction Temperature+150° |
| Output Short-Circuit Duration1sec (Note 1) | Storage Temperature Range65°C to +160°C |
| Continuous Power Dissipation (T _A = +70°C) | Lead Temperature (soldering, 10sec)+300° |
| SOT23-5 (derate 7.1mW/°C above +70°C)571mW | |

Note 1: Avoid shorting OUT to GND, as it may damage the device. For temperatures above +85°C, shorting OUT to GND even instantaneously will damage the device.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = +5.0V, capacitor values from Table 2, T_A = 0^{\circ}C to +85^{\circ}C, unless otherwise noted. Typical values are at T_A = +25^{\circ}C.)$

| PARAMETER | CC | CONDITIONS | | TYP | MAX | UNITS |
|-------------------------------|---------------------------|---------------------------------------------|------|------|------|-------|
| No-Load Supply Current | T _A = +25°C | MAX1682 | | 110 | 145 | μА |
| | 1A = +25 C | MAX1683 | | 230 | 310 | |
| Supply Voltage Range | D. a. a. 10kO | T _A = +25°C | 2.0 | 1.7 | 5.5 | V |
| | $R_{LOAD} = 10k\Omega$ | $T_A = 0^{\circ}C \text{ to } +85^{\circ}C$ | 2.1 | 1.8 | 5.5 | |
| Minimum Operating Voltage | (Note 2) | (Note 2) | | 1 | | V |
| Oscillator Frequency | T _A = +25°C | MAX1682 | 8.4 | 12 | 15.6 | kHz |
| | 1A - +23 C | MAX1683 | 24.5 | 35 | 45.5 | |
| Output Resistance | I _{OUT} = 5mA | T _A = +25°C | | 20 | 50 | Ω |
| | IOUT = SILIA | $T_A = 0^{\circ}C \text{ to } +85^{\circ}C$ | | | 65 | |
| Voltage Conversion Efficiency | $I_{OUT} = 0mA, T_A = +2$ | $I_{OUT} = 0$ mA, $T_{A} = +25$ °C | | 99.9 | | % |

Note 2: Once started, the MAX1682/MAX1683 typically operate down to 1V.

ELECTRICAL CHARACTERISTICS

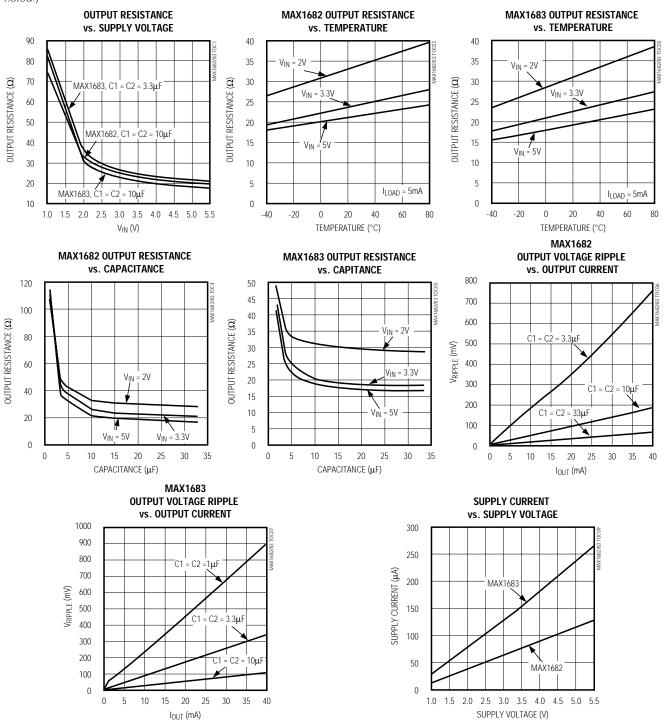
(VIN = +5.0V, capacitor values from Table 2, TA = -40°C to +85°C, unless otherwise noted.) (Note 3)

| PARAMETER | CONDITIONS | MIN T | YP MAX | UNITS | |
|-------------------------------|------------------------|-------|--------|-------|--|
| No-Load Supply Current | MAX1682 | | 160 | | |
| No-Load Supply Current | MAX1683 | | 350 | μΑ | |
| Supply-Voltage Range | $R_{LOAD} = 10k\Omega$ | 2.3 | 5.5 | V | |
| Oscillator Frequency | MAX1682 | 6.6 | 18.6 | kHz | |
| Oscillator Frequency | MAX1683 | 17.5 | 57.8 | KHZ | |
| Output Resistance | I _{OUT} = 5mA | | 65 | Ω | |
| Voltage Conversion Efficiency | I _{OUT} = 0mA | 97 | | % | |

Note 3: Specifications at -40°C to +85°C are guaranteed by design.

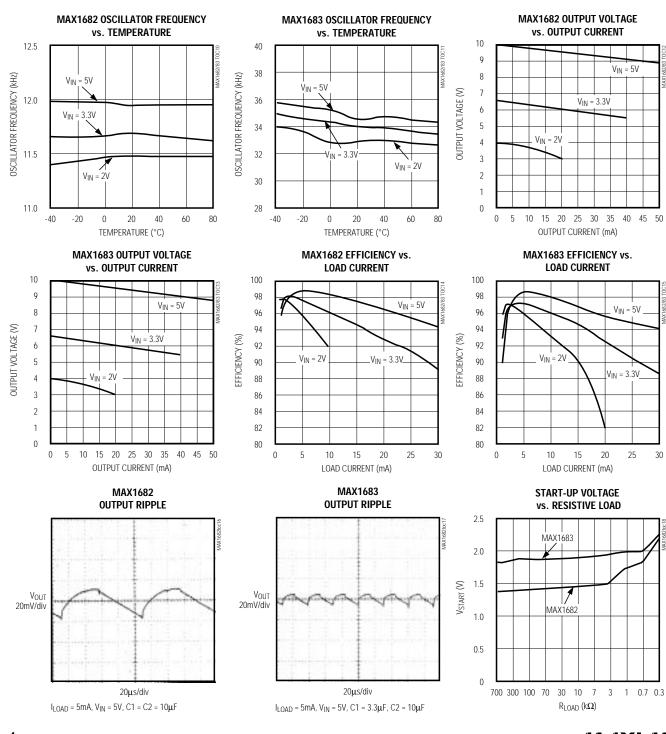
Typical Operating Characteristics

(Typical Operating Circuit, $V_{IN} = +5V$, $C1 = C2 = 10\mu F$ for the MAX1682 and $3.3\mu F$ for the MAX1683, $T_A = +25^{\circ}C$, unless otherwise noted.)



Typical Operating Characteristics (continued)

(Typical Operating Circuit, $V_{IN} = +5V$, $C1 = C2 = 10\mu F$ for the MAX1682 and $3.3\mu F$ for the MAX1683, $T_A = +25^{\circ}C$, unless otherwise noted.)



Pin Description

| PIN | NAME | FUNCTION |
|-----|------|---------------------------------------------------------|
| 1 | GND | Ground |
| 2 | OUT | Doubled Output Voltage. Connect C2 between OUT and GND. |
| 3 | C1- | Negative Terminal of the Flying Capacitor |
| 4 | IN | Input Supply |
| 5 | C1+ | Positive Terminal of the Flying Capacitor |

Detailed Description

The MAX1682/MAX1683 capacitive charge pumps double the voltage applied to their input. Figure 1 shows a simplified functional diagram of an ideal voltage doubler. During the first half-cycle, switches S1 and S2 close, and capacitor C1 charges to V_{IN}. During the second half cycle, S1 and S2 open, S3 and S4 close, and C1 is level shifted upward by V_{IN} volts. This connects C1 to the reservoir capacitor C2, allowing energy to be delivered to the output as necessary. The actual voltage is slightly lower than 2 x V_{IN}, since switches S1–S4 have resistance and the load drains charge from C2.

Charge-Pump Output

The MAX1682/MAX1683 have a finite output resistance of about 20Ω (Table 2). As the load current increases, the devices' output voltage (Vout) droops. The droop equals the current drawn from Vout times the circuit's output impedance (Rs), as follows:

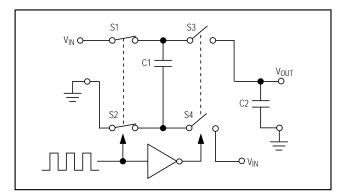


Figure 1. Simplified Functional Diagram of Ideal Voltage Doubler

Efficiency Considerations

The power efficiency of a switched-capacitor voltage converter is affected by three factors: the internal losses in the converter IC, the resistive losses of the capacitors, and the conversion losses during charge transfer between the capacitors. The total power loss is:

The internal losses are associated with the IC's internal functions, such as driving the switches, oscillator, etc. These losses are affected by operating conditions such as input voltage, temperature, and frequency.

The next two losses are associated with the voltage converter circuit's output resistance. Switch losses occur because of the on-resistance of the MOSFET switches in the IC. Charge-pump capacitor losses occur because of their ESR. The relationship between these losses and the output resistance is as follows:

Ppump capacitor losses + Pswitch losses =

$$R_{OUT} \approx \frac{1}{(f_{OSC}) \times C1} + 2R_{SWITCHES} + 4ESR_{C1} + ESR_{C2}$$

where fosc is the oscillator frequency. The first term is the effective resistance from an ideal switchedcapacitor circuit (Figures 2a and 2b).

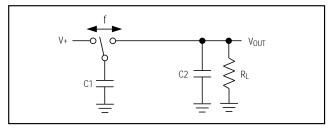


Figure 2a. Switched-Capacitor Model

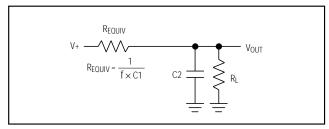


Figure 2b. Equivalent Circuit

Conversion losses occur during the charge transfer between C1 and C2 when there is a voltage difference between them. The power loss is:

$$P_{\text{CONVERSION LOSS}} = \left[\frac{1}{2}C1 \left(4V_{\text{IN}}^{2} - V_{\text{OUT}}^{2} \right) + \frac{1}{2}C2 \left(2V_{\text{OUT}}V_{\text{RIPPLE}} - V_{\text{RIPPLE}}^{2} \right) \right] \times f_{\text{OSC}}$$

where V_{RIPPLE} is the peak-to-peak output voltage ripple determined by the output capacitor and load current (see *Output Capacitor* section). Choose capacitor values that decrease the output resistance (see *Flying Capacitor* section).

Applications Information

Flying Capacitor (C1)

To maintain the lowest output resistance, use capacitors with low ESR. Suitable capacitor manufacturers are listed in Table 1. The charge-pump output resistance is a function of C1 and C2's ESR and the internal switch resistance, as shown in the equation for R_{OUT} in the *Efficiency Considerations* section.

Minimizing the charge-pump capacitor's ESR minimizes the total resistance. Suggested values are listed in Tables 2 and 3.

Using a larger flying capacitor reduces the output impedance and improves efficiency (see the *Efficiency Considerations* section). Above a certain point, increasing C1's capacitance has a negligible effect because the output resistance becomes dominated by the internal switch resistance and capacitor ESR (see the Output Resistance vs. Capacitance graph in the *Typical Operating Characteristics*). Table 2 lists the most desirable capacitor values—those that produce a low output resistance. But when space is a constraint, it may be necessary to sacrifice low output resistance for the sake of small capacitor size. Table 3 demonstrates how the capacitor affects output resistance.

Output Capacitor (C2)

Increasing the output capacitance reduces the output ripple voltage. Decreasing its ESR reduces both output resistance and ripple. Smaller capacitance values can be used with light loads. Use the following equation to calculate the peak-to-peak ripple:

VRIPPLE = IOUT / (fosc x C2) + 2 x IOUT x ESRC2

Input Bypass Capacitor

Bypass the incoming supply to reduce its AC impedance and the impact of the MAX1682/MAX1683's switching noise. When loaded, the circuit draws a continuous current of 2 x IOUT. A $0.1\mu F$ bypass capacitor is sufficient.

Table 1. Recommended Capacitor Manufacturers

| PRODUCTION METHOD | MANUFACTURER | SERIES | PHONE | FAX |
|------------------------|--------------|------------|--------------|--------------|
| | AVX | TPS | 803-946-0690 | 803-448-2170 |
| Surface-Mount Tantalum | Matsuo | 267 | 714-969-2491 | 714-960-6492 |
| | Sprague | 593D, 595D | 603-224-1961 | 603-224-1430 |
| Surface-Mount Ceramic | AVX | X7R | 803-946-0590 | 803-626-3123 |
| Surface-Mount Cerainic | Matsuo | X7R | 714-969-2491 | 714-960-6492 |

Table 2. Suggested Capacitor Values for Low Output Resistance

| PART | FREQUENCY (kHz) | CAPACITOR VALUE (µF) | TYPICAL R _{OUT} (Ω) |
|---------|--------------------|-------------------------|---------------------------------|
| MAX1682 | 12 | 10 | 20 |
| MAX1683 | 35 | 3.3 | 20 |

Table 3. Suggested Capacitor Values for Minimum Size

| PART | FREQUENCY (kHz) | CAPACITOR VALUE (μF) | TYPICAL R _{OUT} (Ω) |
|---------|--------------------|-------------------------|---------------------------------|
| MAX1682 | 12 | 3.3 | 35 |
| MAX1683 | 35 | 1 | 35 |

Cascading Devices

Devices can be cascaded to produce an even larger voltage (Figure 3). The unloaded output voltage is nominally (n + 1) x V_{IN}, where n is the number of voltage doublers used. This voltage is reduced by the output resistance of the first device multiplied by the quiescent current of the second. The output resistance increases when devices are cascaded. Using a two-stage doubler as an example, output resistance can be approximated as R_{OUT} = 2 x R_{OUT1} + R_{OUT2}, where R_{OUT1} is the output resistance of the first stage and R_{OUT2} is the output resistance of the second stage. A typical value for a two-stage voltage doubler is 60Ω (with C1 at 10μ F for MAX1682 and 3.3μ F for MAX1683). For n stages with the same C1 value, R_{OUT} = $(2^{n} - 1)$ x R_{OUT1}.

Paralleling Devices

Paralleling multiple MAX1682 or MAX1683s reduces the output resistance. Each device requires its own pump capacitor (C1), but the reservoir capacitor (C2) serves all devices (Figure 4). Increase C2's value by a factor of n, where n is the number of parallel devices. Figure 4 shows the equation for calculating output resistance.

Layout and Grounding

Good layout is important, primarily for good noise performance. To ensure good layout, mount all components as close together as possible, keep traces short to minimize parasitic inductance and capacitance, and use a ground plane.

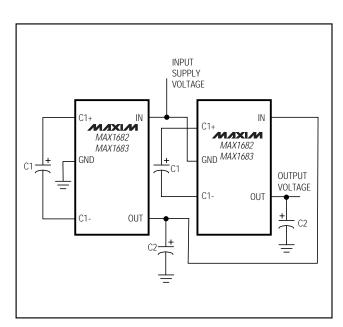


Figure 3. Cascading Devices

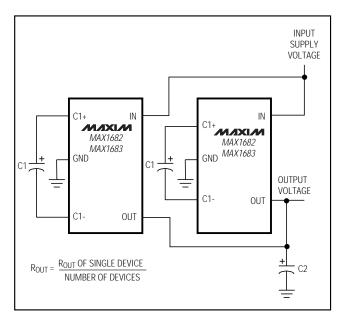


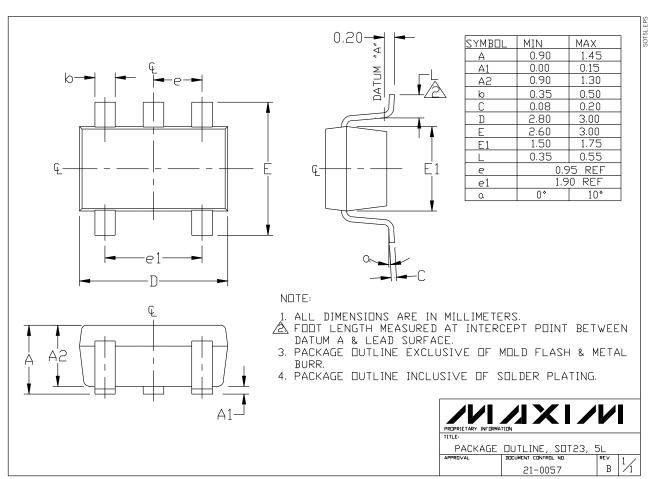
Figure 4. Paralleling Devices

_____Chip Information

TRANSISTOR COUNT: 97

SUBSTRATE CONNECTED TO OUT

Package Information



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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